SILICON EPITAXIAL PLANAR SWITCHING DIODE

Features

- Fast switching diode
- Ultra small surface mount package





SOT-323 Plastic Package Marking Code: A4

Absolute Maximum Ratings (T₂ = 25 °C)

Parameter		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V_{RM}	100	V
Reverse Voltage		V_R	75	V
Continuous Forward Current	ngle diode loaded ouble diode loaded	I _F	175 100	mA
Repetitive Peak Forward Current		I _{FRM}	500	mA
Non-Repetitive Peak Forward Current	at t = 1 µs at t = 1 ms at t = 1 s	I _{FSM}	4 1 0.5	А
Power Dissipation		P _{tot}	200	mW
Junction Temperature		TJ	150	°C
Storage Temperature Range		T _s	- 65 to + 150	°C

Characteristics at T_a = 25 °C

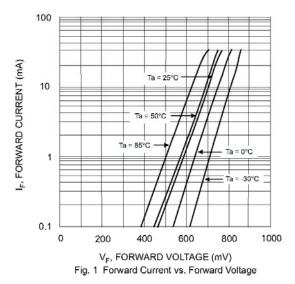
Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I_R = 100 μA	$V_{BR(R)}$	75	-	V
Forward Voltage at I_F = 1 mA at I_F = 10 mA at I_F = 50 mA at I_F = 150 mA	V _F	- - - -	0.715 0.855 1 1.25	V
Reverse Leakage Current at V_R = 25 V at V_R = 75 V at V_R = 25 V, T_J = 150 °C at V_R = 75 V, T_J = 150 °C	I _R	- - - -	30 2.5 60 100	nA μA μA μA
Diode Capacitance at $V_R = 0 V$, $f = 1 MHz$	C _{tot}	-	2	pF
Reverse Recovery Time at I_F = 10 mA to I_R = 10 mA, I_{rr} = 0.1 I_R , R_L = 100 Ω	t _{rr}	-	4	ns





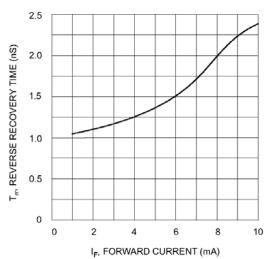






10.0 Ta = 100°C IR, REVERSE CURRENT (µA) 1.0 0.10 0.01 0.001 40 60 80 20

V_R, REVERSE VOLTAGE (V) Fig. 2 Reverse Current vs Reverse Voltage



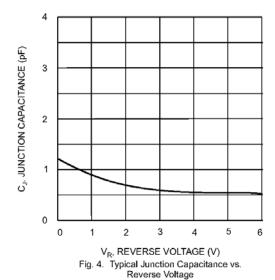


Fig. 3. Reverse Recovery Time vs. Forward Current









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